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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : Hartwig RICHTER et al.
Serial No. : 09/529,700
Filed : April 18, 2000
Title : SEMICONDUCTOR LASER CHIP
Art Unit : 2828
Examiner : James Davie

Commissioner for Patents
Washington, D.C. 20231

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231 on

Date: March 13, 2003

Signature:

Linda M. Shudy (Reg. no. 47,084)

AMENDMENT

Sir:

In response to the Office Action mailed on September 13, 2002, please reconsider the above-identified application based on the following:

IN THE CLAIMS:

Please cancel without prejudice claims 17 and 18.

Please amend without prejudice claims 16, 21, 26 and 32 as follows:

16. (Twice amended) A semiconductor laser comprising:

a semiconductor laser chip; and

at least one temperature sensor configured to be integrated in the semiconductor laser chip for measuring an operating temperature,

wherein the at least one temperature sensor is secured by welding directly in the semiconductor laser chip, an energy for the welding coming from a light source, the light source including at least one of a ND-glass source, a Nd-YAG source and a source having a similar spatial distribution and similar spectral distribution to a Nd-glass source or a Nd-YAG source.

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19. (Amended) The semiconductor laser as recited in claim 16 wherein prior to the welding